

**SOP-8 N Channel Enhancement 沟道增强型  
MOS Field Effect Transistor 场效应管**

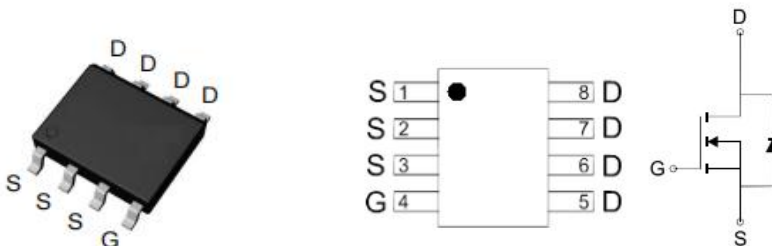
**■ Features 特点**

Low on-resistance 低导通电阻  
 $R_{DS(ON)}=15m\Omega(\text{Type})@V_{GS}=10V$   
 $R_{DS(ON)}=20m\Omega(\text{Type})@V_{GS}=4.5V$

**■ Applications 应用**

Load Switch 负载开关  
 DC-DC Conversion 升压转换  
 Synchronous Rectification 同步整流

**■ Internal Schematic Diagram 内部结构**



**■ Absolute Maximum Ratings 最大额定值**

| Characteristic 特性参数                    | Symbol 符号   | Rat 额定值  | Unit 单位      |
|--|---|----------|--------------|
| Drain-Source Voltage 漏极-源极电压           | $BV_{DSS}$  | 100      | V            |
| Gate- Source Voltage 栅极-源极电压           | $V_{GS}$  | $\pm 20$ | V            |
| Drain Current (continuous)漏极电流-连续      | $I_D$ (at $T_A = 25^\circ C$<br>at $T_A = 70^\circ C$ ) | 10<br>8  | A            |
| Drain Current (pulsed)漏极电流-脉冲          | $I_{DM}$  | 40       | A            |
| Total Device Dissipation 总耗散功率         | $P_{TOT}(\text{at } T_A = 25^\circ C)$                  | 3        | W            |
| Avalanche Energy(Single Pulse)雪崩能量     | $E_{AS}$  | 36       | mJ           |
| Thermal Resistance Junction-Ambient 热阻 | $R_{\theta JA}$   | 42       | $^\circ C/W$ |
| Junction/Storage Temperature 结温/储存温度   | $T_J, T_{stg}$  | -55~150  | $^\circ C$   |

■ Electrical Characteristics 电特性

( $T_A=25^{\circ}\text{C}$  unless otherwise noted 如无特殊说明, 温度为  $25^{\circ}\text{C}$ )

| Characteristic<br>特性参数  | Symbol<br>符号 | Min<br>最小值 | Typ<br>典型值 | Max<br>最大值 | Unit<br>单位       |
|---|--------------|------------|------------|------------|------------------|
| Drain-Source Breakdown Voltage<br>漏极-源极击穿电压( $I_D=250\mu\text{A}, V_{GS}=0\text{V}$ )   | $BV_{DSS}$   | 100        | —          | —          | V                |
| Gate Threshold Voltage<br>栅极开启电压( $I_D=250\mu\text{A}, V_{GS}=V_{DS}$ )   | $V_{GS(th)}$ | 1.4        | 2          | 3          | V                |
| Zero Gate Voltage Drain Current<br>零栅压漏极电流( $V_{GS}=0\text{V}, V_{DS}=100\text{V}$ )  | $I_{DSS}$    | —          | —          | 1          | $\mu\text{A}$    |
| Gate Body Leakage<br>栅极漏电流( $V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$ )   | $I_{GSS}$    | —          | —          | $\pm 100$  | nA               |
| Static Drain-Source On-State Resistance<br>静态漏源导通电阻( $I_D=10\text{A}, V_{GS}=10\text{V}$ )<br>( $I_D=8\text{A}, V_{GS}=4.5\text{V}$ ) | $R_{DS(ON)}$ | —          | 15<br>20   | 18<br>24   | $\text{m}\Omega$ |
| Diode Forward Voltage Drop<br>内附二极管正向压降( $I_{SD}=10\text{A}, V_{GS}=0\text{V}$ )  | $V_{SD}$     | —          | 0.76       | 1          | V                |
| Input Capacitance 输入电容<br>( $V_{GS}=0\text{V}, V_{DS}=30\text{V}, f=1\text{MHz}$ )  | $C_{ISS}$    | —          | 980        | 1320       | pF               |
| Common Source Output Capacitance<br>共源输出电容( $V_{GS}=0\text{V}, V_{DS}=30\text{V}, f=1\text{MHz}$ )                                    | $C_{OSS}$    | —          | 150        | —          | pF               |
| Reverse Transfer Capacitance<br>反馈电容( $V_{GS}=0\text{V}, V_{DS}=30\text{V}, f=1\text{MHz}$ )  | $C_{RSS}$    | —          | 85         | —          | pF               |
| Total Gate Charge 栅极电荷密度<br>( $V_{DS}=30\text{V}, I_D=8\text{A}, V_{GS}=10\text{V}$ )   | $Q_g$        | —          | 50         | 65         | nC               |
| Gate Source Charge 栅源电荷密度<br>( $V_{DS}=30\text{V}, I_D=8\text{A}, V_{GS}=10\text{V}$ )  | $Q_{gs}$     | —          | 8          | —          | nC               |
| Gate Drain Charge 栅漏电荷密度<br>( $V_{DS}=30\text{V}, I_D=8\text{A}, V_{GS}=10\text{V}$ )   | $Q_{gd}$     | —          | 10         | —          | nC               |
| Turn-ON Delay Time 开启延迟时间<br>( $V_{DS}=30\text{V}, I_D=1\text{A}, R_{GEN}=6\Omega, V_{GS}=10\text{V}$ )                               | $t_{d(on)}$  | —          | 18         | 33         | ns               |
| Turn-ON Rise Time 开启上升时间<br>( $V_{DS}=30\text{V}, I_D=1\text{A}, R_{GEN}=6\Omega, V_{GS}=10\text{V}$ )                                | $t_r$        | —          | 9          | 17         | ns               |
| Turn-OFF Delay Time 关断延迟时间<br>( $V_{DS}=30\text{V}, I_D=1\text{A}, R_{GEN}=6\Omega, V_{GS}=10\text{V}$ )                              | $t_{d(off)}$ | —          | 56         | 101        | ns               |
| Turn-OFF Fall Time 关断下降时间<br>( $V_{DS}=30\text{V}, I_D=1\text{A}, R_{GEN}=6\Omega, V_{GS}=10\text{V}$ )                               | $t_f$        | —          | 14         | 26         | ns               |

■ Typical Characteristic Curve 典型特性曲线

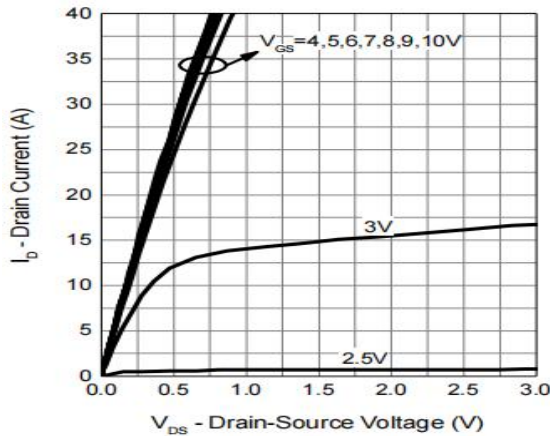


Figure 1: Output Characteristics

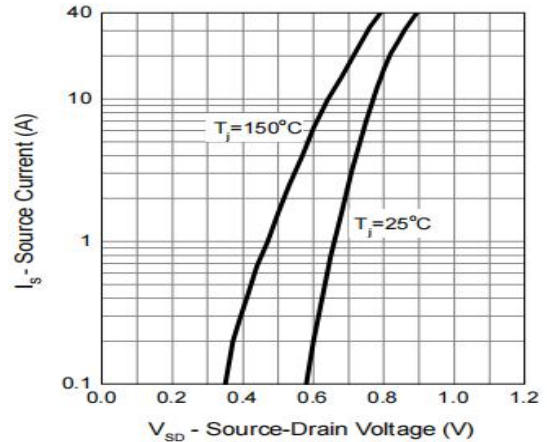


Figure 2: Diode Forward Characteristics

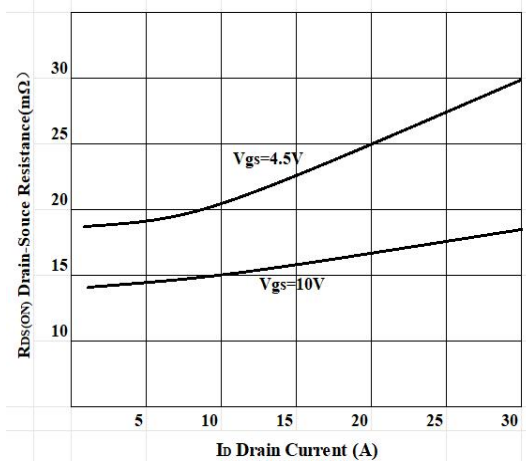


Figure 3: On-Resistance vs.  $I_D$

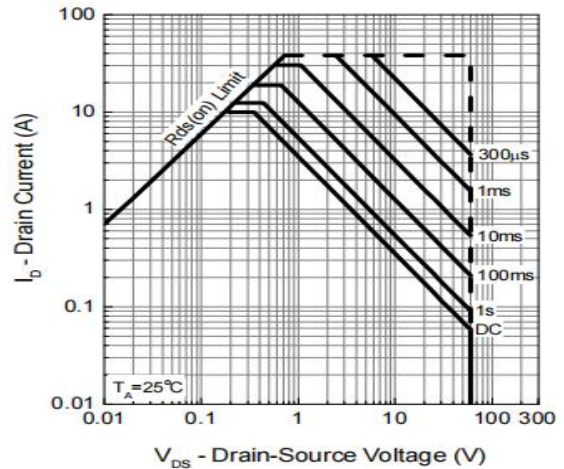


Figure 4: Safe Operating Area

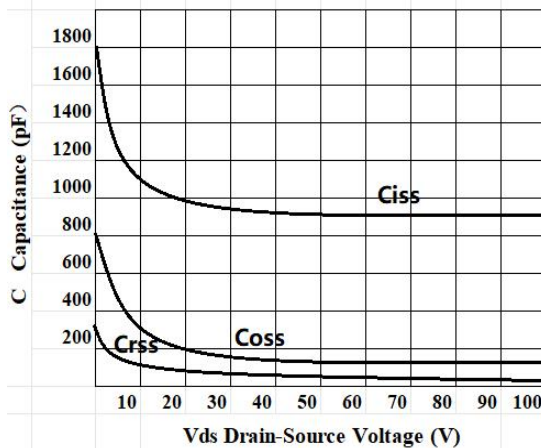


Figure 5: Capacitance Characteristics

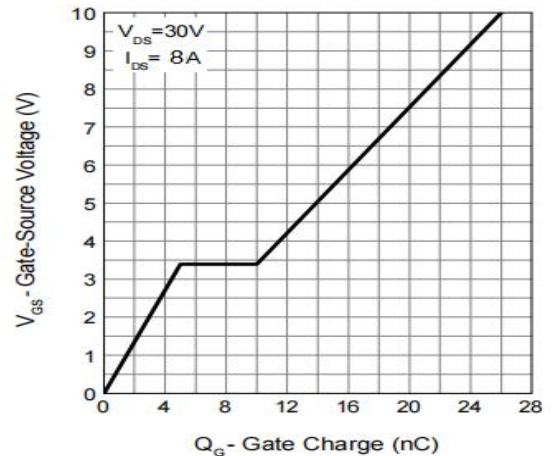
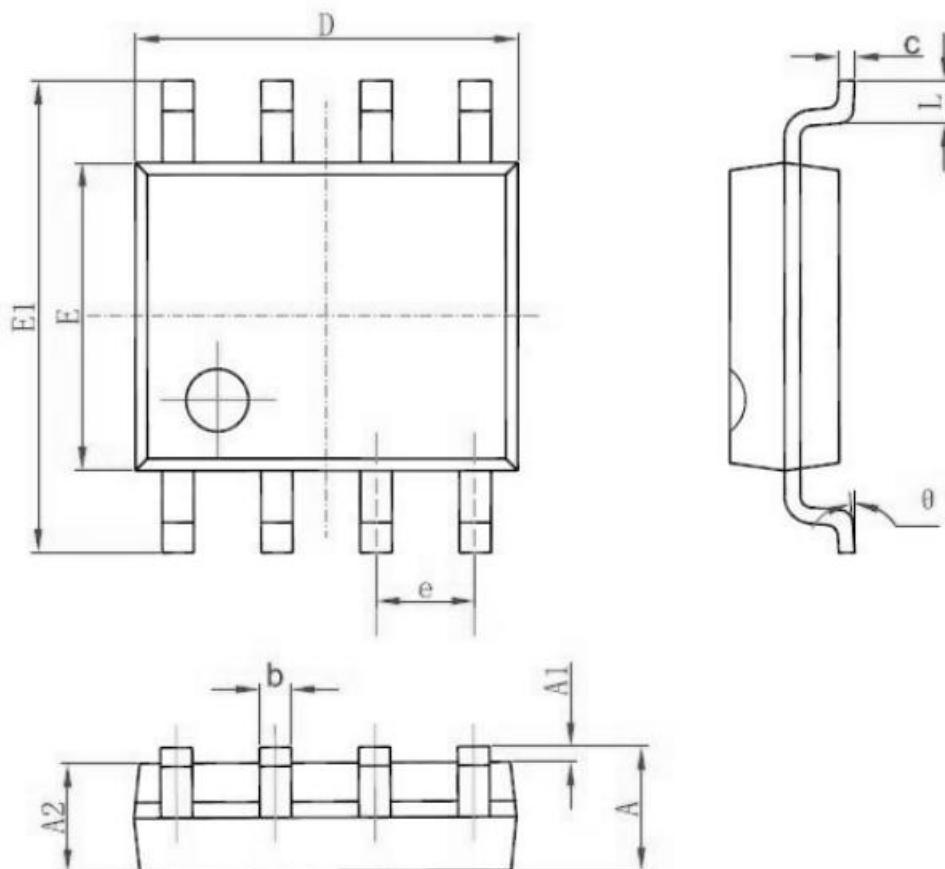


Figure 6: Gate-Charge Characteristics

■ Dimension 外形封装尺寸



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.006                | 0.010 |
| D      | 4.700                     | 5.100 | 0.185                | 0.200 |
| E      | 3.800                     | 4.000 | 0.150                | 0.157 |
| E1     | 5.800                     | 6.200 | 0.228                | 0.244 |
| e      | 1.270 (BSC)               |       | 0.050 (BSC)          |       |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |